

Part Number: **DMP3xxxLSS-13**
Weight (mg): 76.4042

Part **DMP3015LSS-13, DMP3020LSS-13,**
Numbers: **DMP3035LSS-13, DMP3056LSS-13**

Element	Material Group	Materials	CAS (if applicable)	Average mass homogeneous Material(%)	Percent of whole (%)	Mass (mg)	ppm Homogeneous Material	ppm overall
Chip	Silicon w/Metal	Doped Silicon*	7440-21-3	100.00%	4.07	3.11	1000000	40718
Leadframe	Alloy 42	Fe	7439-89-6	57.65%	51.08	39.03	576500	294486
		Ni	7440-02-0	41.00%			410000	209435
		Mn	7439-96-5	0.60%			6000	3065
		Cr(not Cr 6+)	7440-47-3	0.10%			1000	511
		Co	7440-48-4	0.50%			5000	2554
		Si	7440-21-3	0.15%			1500	766
Leadframe Plating	Silver	Silver	7440-22-4	100.00%	0.93	0.71	1000000	9345
Bond Wire	Copper Wire	Copper	7440-50-8	100.00%	1.04	0.80	1000000	10430
Encapsulation	EME-G700	Epoxy Resin	-----	7.50%	39.00	29.80	75000	29254
		Phenol Resin	-----	5.00%			50000	19502
		Bismuth/Bismuth compound	-----	0.05%			500	195
		SiO2	60676-86-0	86.95%			869500	339147
		C	1333-86-4	0.50%			5000	1950
Die Attach Epoxy	84-1LMISR4	Ag	7440-22-4	75.00%	1.64	1.25	750000	12300
		epoxy resin	Trade secret	20.00%			200000	3280
		curing agent & hardener	Trade secret	5.00%			50000	820
Lead Plating Finish	Matte Tin	Tin	7440-31-5	100.00%	2.22	1.70	1000000	22242
				Total	100.00	76.40		1000000

Tolerance ±10%

This data is based on information provided by our suppliers. We believe it to be correct but do not routinely validate it by measurement. It is for guidance only and Diodes Inc. does not guarantee its absolute accuracy or completeness

* The Silicon Chip is doped at atomic levels with trace amounts of elements that may include Phosphorus, Boron, Arsenic, and other elements. Metalization may include Titanium, Nickel, Aluminum, Silver or Gold. These substances are not reported where their concentration is less than the minimum reportable level per the guidelines specified in the Tables of EIA JIG-101, Material Composition Declaration for Electronic Products.

This product or product family does not contain any of the following substances except as **CURRENTLY** exempted by ELV II and RoHS and reported above:

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| Asbestos | Ozone Depleting Substances - Class I (CFCs, HBFCs, etc.) |
| Azo compounds | Ozone Depleting Substances - Class II (HCFCs) |
| Cadmium and cadmium compounds | Perfluorooctane Sulphonate (PFOS) or related compounds |
| Certain Shortchain Chlorinated Paraffins | Polybrominated biphenyls (PBB) and Polybrominated diphenyl ethers (PBDE) including DecaBDE |
| Chlorinated organic compounds | Polychlorinated Biphenyls (PCBs) |
| Hexavalent chromium compounds | Polychlorinated Naphthalenes (> 3 chlorine atoms) |
| Lead and lead compounds | Radioactive Substances |
| Mercury and mercury compounds | Tributyl Tin (TBT) and Triphenyl Tin (TPT) |
| Organic tin compounds | Tributyl Tin Oxide (TBTO) |